TS74230L - 30W CW GaN Broadband RF Switch SPDT

1.0 Features

- Low insertion loss: 0.40dB @ 800MHz
- High isolation: 43dB @ 800MHz
- High linear power handling capability
- Versatile 2.6-5.5V Vdd power supply
- Vcp supply of -18V
- 43dBm Hot Switching Capable

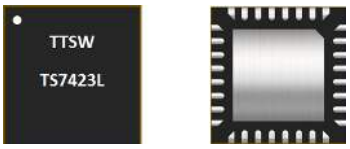

Figure 1 Device Image
(32 Pin 4×4×0.8mm QFN Package)

2.0 Applications

- Private Mobile radio handsets
- Public safety handsets
- Cellular infrastructure
- Small cells
- LTE relays and microcells

RoHS/REACH/Halogen Free Compliance

3.0 Description

The TS74230L is a symmetrical reflective Single Pole Dual Throw (SPDT) switch designed for broadband, high peak power switching applications. Its broadband behavior from 1MHz to 3GHz makes the TS74230L an excellent switch for all the applications requiring low insertion loss, high isolation and high linearity within a small package size. This part has the internal charge pump disabled to eliminate the charge pump spurs. A -17 to -18V supply is needed on the VCP pin.

The TS74230L is packaged into a compact Quad Flat No lead (QFN) 4x4mm 32 leads plastic package.

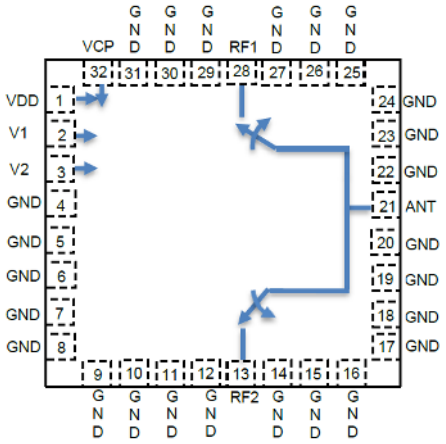

Figure 2 Function Block Diagram
(Top View)

4.0 Ordering Information

Table 1 Ordering Information

Base Part Number	Package Type	Form	Qty	Reel Diameter	Reel Width	Orderable Part Number
TS74230L	32 Pin 4×4×0.8mm QFN	Tape and Reel	3000	13” (330mm)	18mm	TS74230LMTRPBF
Evaluation Board						TS74230L-EVB

5.0 Pin Description

Table 2 Pin Definition

Pin Number	Pin Name	Description
1	VDD	DC power supply
2	V1	Switch control input 1
3	V2	Switch control input 2
4,5,6,7,8,9,10,11,12,14,15,16,17, 18,19,20,22,23,24,25,26,27,29,30,31	NC	No internal connection, Can be grounded
13	RF2	RF port 2
21	ANT	Antenna port
28	RF1	RF port 1
32	VCP	Negative Voltage Supply, -17 to -18V

Note: The backside ground (thermal) pad of the package must be grounded directly to the ground plane of PCB with multiple vias to ensure proper operation and thermal management.

6.0 Absolute Maximum Ratings

Table 3 Absolute Maximum Ratings @T_A=+25°C Unless Otherwise Specified

Parameter	Symbol	Value	Unit
Electrical Ratings			
Power Supply Voltage Vdd	VDD	2.6 to 5.5	V
Charge Pump Voltage Vcp	Vcp	-15 to -19	V
Storage Temperature Range	T_{st}	-55 to +125	°C
Operating Temperature Range	T_{op}	-40 to +85	°C
Maximum Junction Temperature	T_J	+140	°C
RF Input Power CW, 20-3000MHz, T_C=+85°C	RFx	45	dBm
RF Input Power (VSWR 10:1), 1 minute	RFx	44	dBm
Thermal Ratings			
Thermal Resistance (junction-to-case) – Bottom side	$R_{\theta JC}$	10	°C/W
Thermal Resistance (junction-to-top)	$R_{\theta JT}$	≤ 37	°C/W
Soldering Temperature	T_{SOLD}	260	°C
ESD Ratings			
Human Body Model (HBM)	Level 1B	500 to <1000	V
Charged Device Model (CDM)	Level C3	≥1000	V
Moisture Rating			
Moisture Sensitivity Level	MSL	1	-

Attention:
Maximum ratings are absolute ratings. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding one or a combination of the absolute maximum ratings may cause permanent and irreversible damage to the device and/or to surrounding circuit.

7.0 Electrical Specifications

Table 4 Electrical Specifications @T_A=+25°C Unless Otherwise Specified; VDD=+2.7V; VCP= -18V; 50Ω Source/Load.

Parameter	Condition	Minimum	Typical	Maximum	Unit
Operating Frequency		1		3000	MHz
Insertion Loss, RFx	400MHz		0.35		dB
	800MHz		0.40	0.5	
	1.95GHz		0.45	0.6	
	2.6GHz		0.50	0.7	
Isolation, ANT-RFx	400MHz		50		dB
	800MHz	40	43		
	1.95GHz	32	34		
	2.6GHz	28	30		
Return Loss, ANT-RFx	400MHz		30		dB
	800MHz		28		
	1.95GHz		25		
	2.6GHz		25		
H2	800MHz, Pin=40dBm		-83		dBc
H3	800MHz, Pin=40dBm		-81		dBc
IIP3	800MHz		74		dBm
P0.1dB[1]	0.1dB compression point, 20MHz - 3GHz		46		dBm
P0.1dB[1]	0.1dB compression point, 1 - 10MHz		43.5		dBm
Switching Time	50% ctrl to 10/90% of the RF value is settled. C1=1nF (refer to Figure 3)		2.0		μs
Control Voltage	Power supply VDD	2.6	3.3	5.5	V
	Charge Pump Supply Voltage VCP	-19	-18	-15	V
	All control pins high, V_{ih}	1.0	3.3	5.25	V
	All control pins low, V_{il}	-0.3		0.5	V
Control Current	All control pins low, I_{il}		0		μA
	All control pins high, I_{ih}			7.5	μA
Current Consumption, IDD	Active mode		160	200	μA

Note: [1] P0.1dB is a figure of merit.

[2] No external DC blocking capacitors required on RF pins unless DC voltage is applied on a RF pin.

8.0 Switch Truth Table

Table 5 Switch Truth Table

V1	V2	Active RF Path
0	1	All OFF
0	0	ANT-RF1
1	0	ANT-RF2

Bias Sequence:
[1] **VDD should be applied first before VCP.** Minimum time between VDD and VCP should be 50usec.
[2] Vc can be applied/toggled after VCP voltage has settled.

9.0 Evaluation Board Schematic

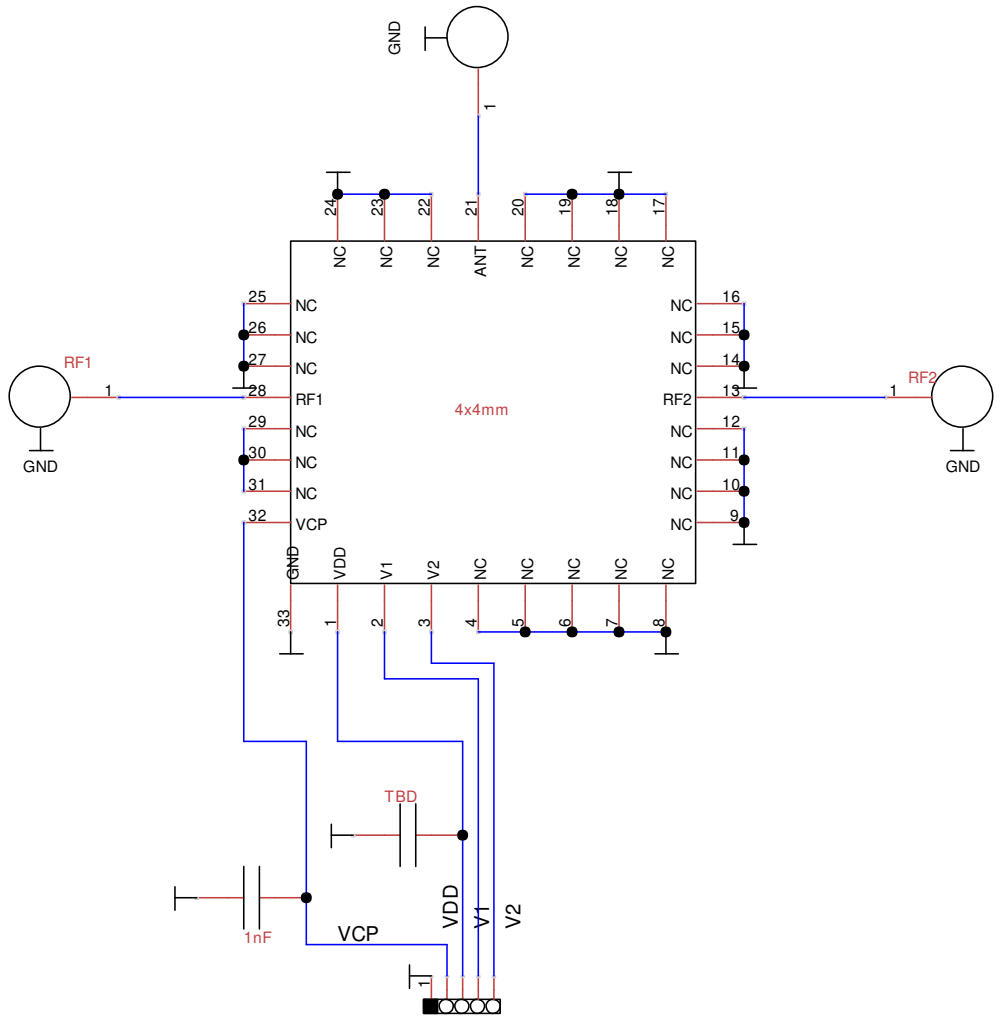

Figure 3 Evaluation Board Schematic

Attention:
[1] 33 refers to the center pad of the device which is ground.
[2] -17/-18V needed on VCP pin.

10.0 Typical Characteristics

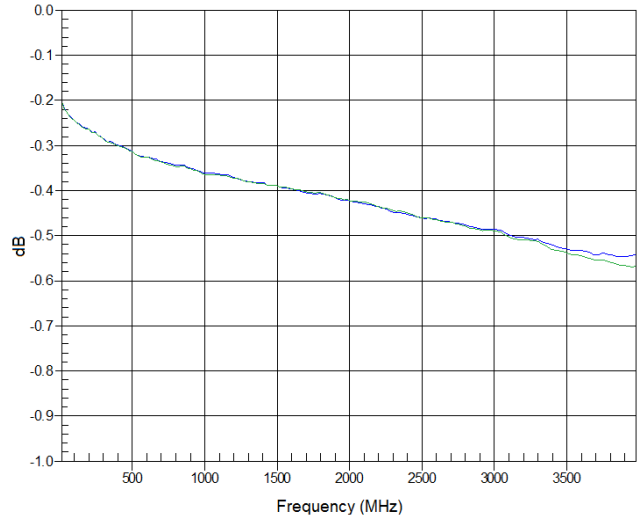

Figure 4 RF1, RF2 Insertion Loss

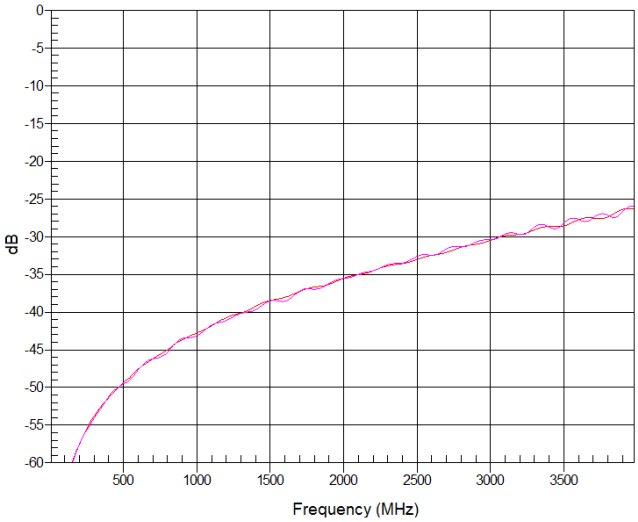

Figure 5 RF1, RF2 Isolation

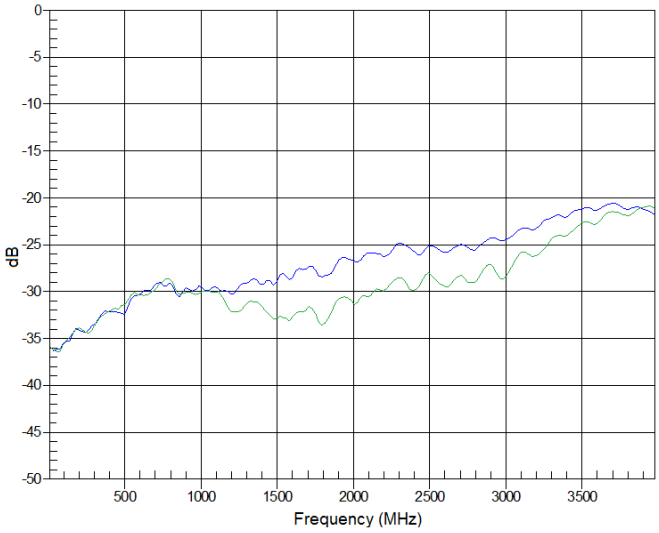

Figure 6 RF1, RF2 Return Loss

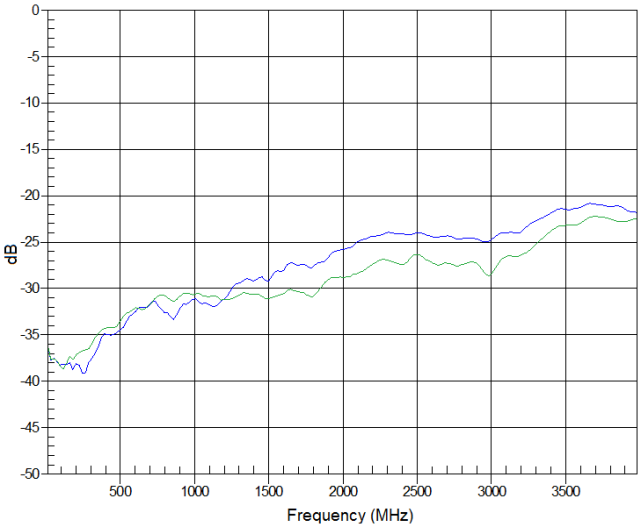

Figure 7 ANT Return Loss

11.0 Device Package Information

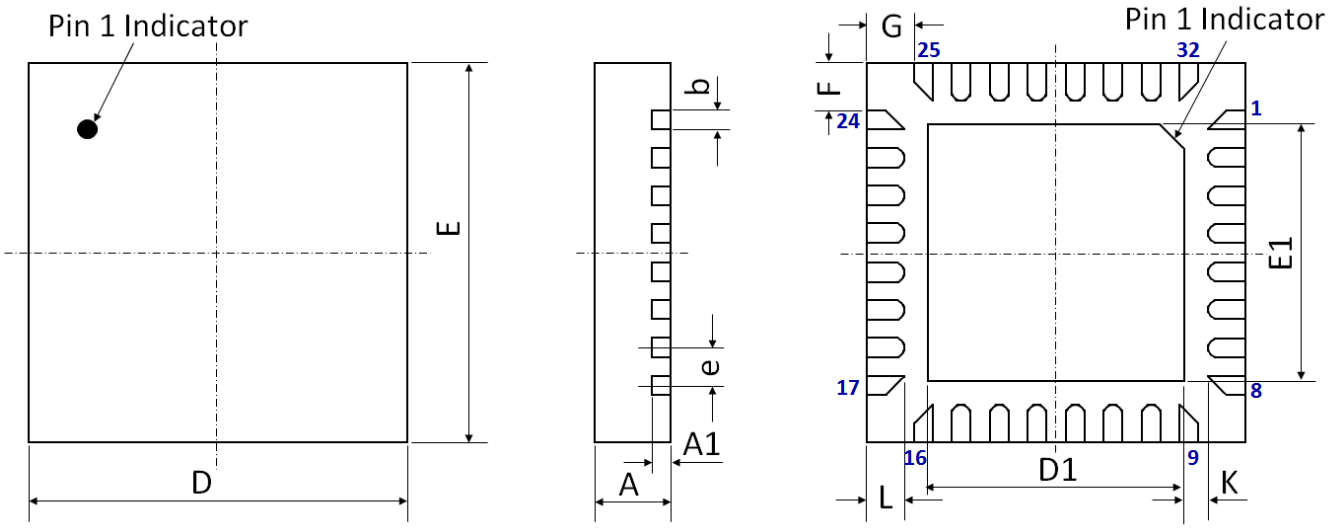

Figure 8 Device Package Drawing
(All dimensions are in mm)

Table 6 Device Package Dimensions

Dimension (mm)	**Value** (mm)	**Tolerance** (mm)	**Dimension** (mm)	**Value** (mm)	**Tolerance** (mm)
A	0.80	±0.05	E	4.00 BSC	±0.05
A1	0.203	±0.02	E1	2.70	±0.05
b	0.20	+0.05/-0.07	F	0.50	±0.05
D	4.00 BSC	±0.05	G	0.50	±0.05
D1	2.70	±0.05	L	0.40	±0.05
e	0.40 BSC	±0.05	K	0.25	±0.05

Note: Lead finish: Pure Sn without underlayer; Thickness: 7.5μm ~ 20μm (Typical 10μm ~ 12μm)

Attention:
Please refer to application notes *TN-001* and *TN-002* at http://www.tagoretech.com for PCB and soldering related guidelines.

12.0 PCB Land Design

Guidelines:
[1] 4 layer PCB is recommended.
[2] Via diameter is recommended to be 0.2mm to prevent solder wicking inside the vias.
[3] Thermal vias shall only be placed on the center pad.
[4] The maximum via number for the center pad is 6(X)×6(Y)=36.

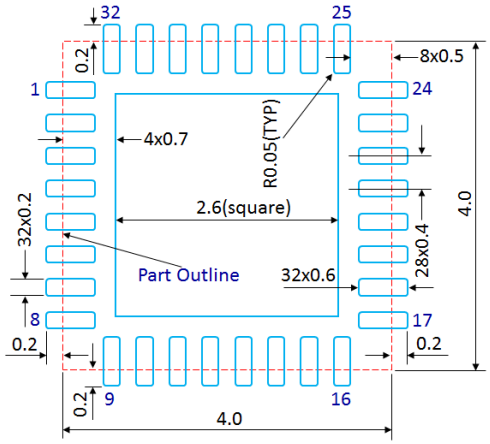

Figure 9 PCB Land Pattern
(Dimensions are in mm)

Non-Solder Mask Defined (Preferred)

Solder Mask Defined

Figure 10 Solder Mask Pattern
(Dimensions are in mm)

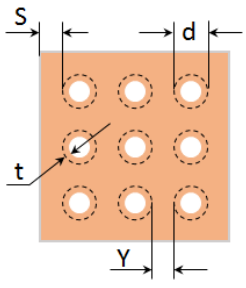

Figure 11 Thermal Via Pattern
(Recommended Values: S≥0.15mm; Y≥0.20mm; d=0.2mm; Plating Thickness t=25μm or 50μm)

13.0 PCB Stencil Design

Guidelines:

[1] Laser-cut, stainless steel stencil is recommended with electro-polished trapezoidal walls to improve the paste release.

[2] Stencil thickness is recommended to be 125µm.

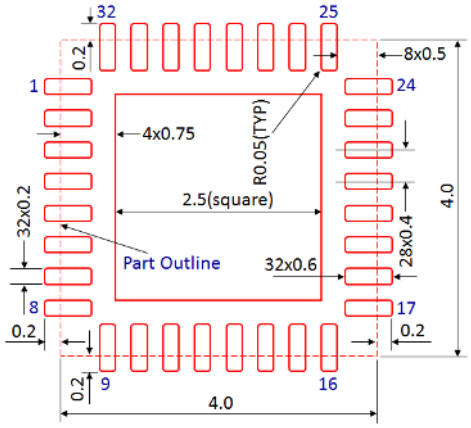

Figure 12 Stencil Openings
(Dimensions are in mm)

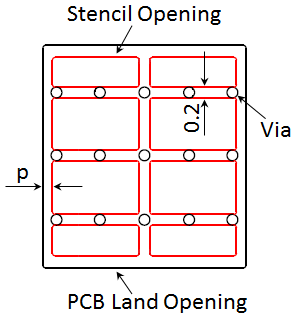

Figure 13 Stencil Openings Shall not Cover Via Areas If Possible
(Dimensions are in mm)

14.0 Tape and Reel Information

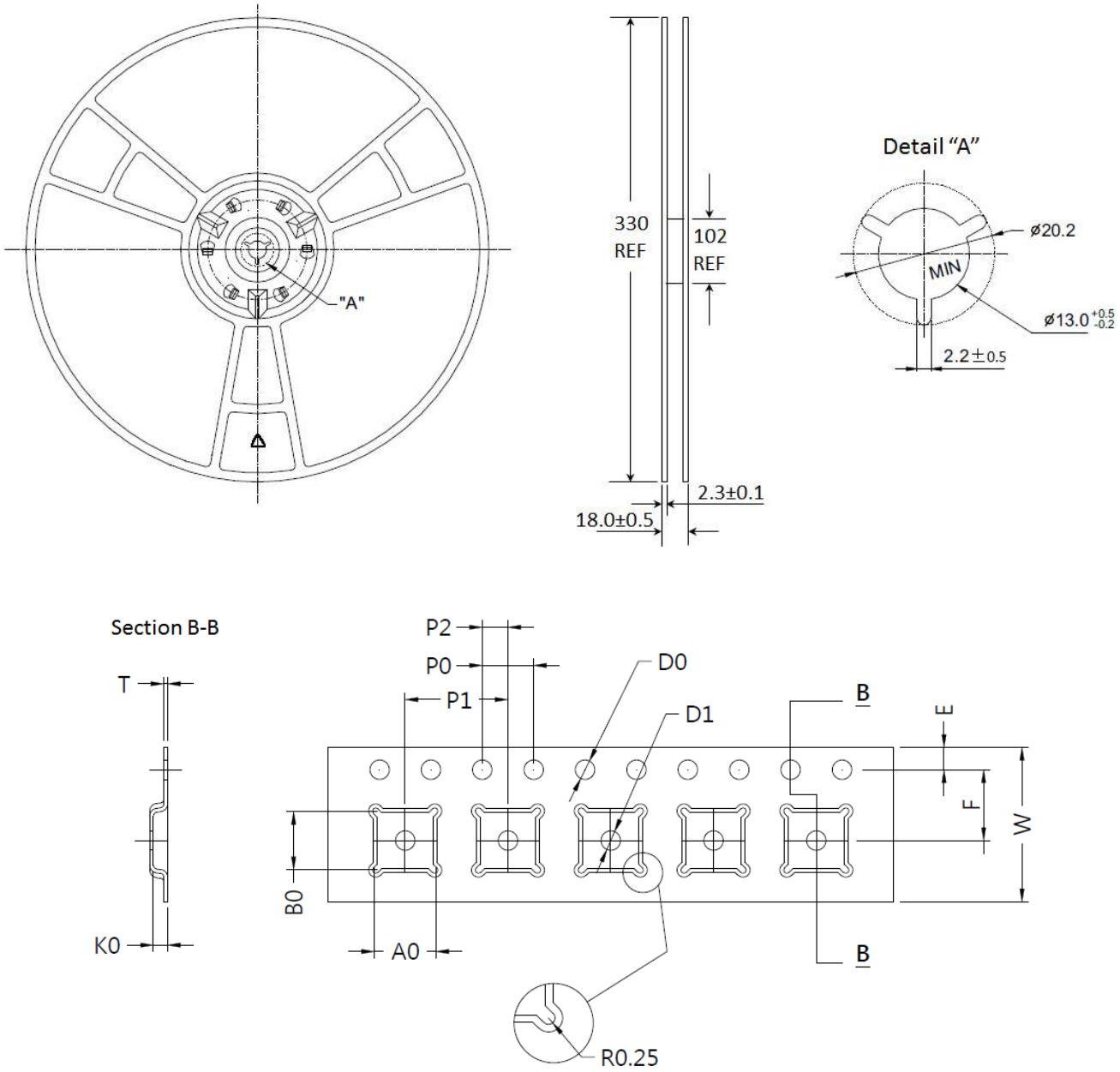

Figure 14 Tape and Reel Drawing

Table 7 Tape and Reel Dimensions

Dimension (mm)	**Value** (mm)	**Tolerance** (mm)	**Dimension** (mm)	**Value** (mm)	**Tolerance** (mm)
A0	4.35	±0.10	K0	1.10	±0.10
B0	4.35	±0.10	P0	4.00	±0.10
D0	1.50	+0.10/-0.00	P1	8.00	±0.10
D1	1.50	+0.10/-0.00	P2	2.00	±0.05
E	1.75	±0.10	T	0.30	±0.05
F	5.50	±0.05	W	12.00	±0.30

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